



Call for Papers

2019 Asia-Pacific Microwave Conference (APMC) and Technical Exhibition in Singapore

Active Devices and Circuits

Low-noise devices and circuits, high-power devices and circuits, wide band-gap devices, microwave tubes, control circuits (mixer, oscillator, switch, etc.), MMICs, RFICs, millimeter and THz wave devices and circuits, graphene devices, and other relevant topics.

Passive Components

Multiband, broadband, tunable, and reconfigurable filters, resonators, directional couplers and hybrids, waveguides and transmission lines, ferrite and SAW devices, RF MEMS, LTCC devices, packaging, metamaterials and EBG structures, plasmonic and optical components, nanomaterials, and other relevant topics.

Systems

5G systems, high-speed and broadband millimeter and THz wave systems, MIMO systems, microwave photonics, radar and sensor systems, IoT/M2M/RFID systems, wearable devices and systems, security and health monitoring systems, wireless power transfer systems, energy harvesting devices and systems, microwave medical and biomedical applications systems, whitespace systems, software defined/cognitive/smart radio systems, satellite systems, near/far field measurement, EMC/EMI, SI/PI, microwave heating and chemistry, and other relevant topics.

Antennas and Propagation

EM field theory, EM wave propagation, wave scattering and inverse scattering, DOA estimation, localization, antenna theory and design, millimeter-wave/THz and optical antennas, small antennas, broadband and multi-band antennas, MIMO antennas, active adaptive and smart antennas, reconfigurable antennas, body channel modelling, and other relevant topics.

Emerging Areas

Nano-electromagnetics, artificial intelligence, machine learning and deep learning for microwave and wireless applications, electromagnetic-acoustics, and other relevant topics.

All accepted and presented papers will be included and published in IEEE Xplore.

Technical Exhibition

The Technical Exhibition on RF/microwave/EMC components, devices, materials, measurements, instrumentation and software will be the major accompanying event of the Asia-Pacific Microwave Week.

This exhibition will provide a diverse array of opportunities to showcase and network with tech companies in an exciting venue hosting major manufacturers and distributors of RF/microwave-related equipment, software, and tools.

Important Dates

Table with 2 columns: Event description and Date. Includes: Proposals for special sessions & workshops and tutorials (June 10, 2019), Preliminary paper submission (3 pages in PDF format) (June 30, 2019), Notification of acceptance (August 30, 2019), Final paper submission (September 20, 2019).



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